

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1-8. (canceled).

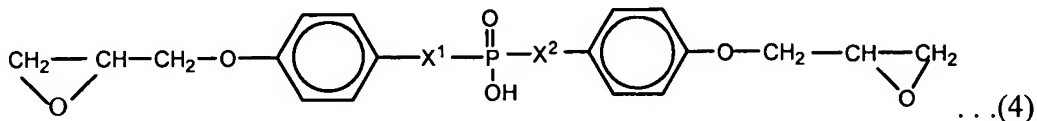
9. (previously presented): A multilayered printed circuit board comprising:  
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer, wherein said solder resist layer contains an elastomer component in a composition comprising a resin for said solder resist layer, and  
said elastomer component is separated in micro-phase as to form an island-in-sea structure after curing in said solder resist layer.

10-31. (canceled).

32. (previously presented): A multilayered printed circuit board comprising:  
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer, wherein said solder resist layer contains a P atom-containing epoxy resin,

said P atom-containing epoxy resin has bivalent phosphoric acid residue, and has epoxy groups in both terminals of the P atom-containing epoxy resin, and

said epoxy resin has the following general formula (4)

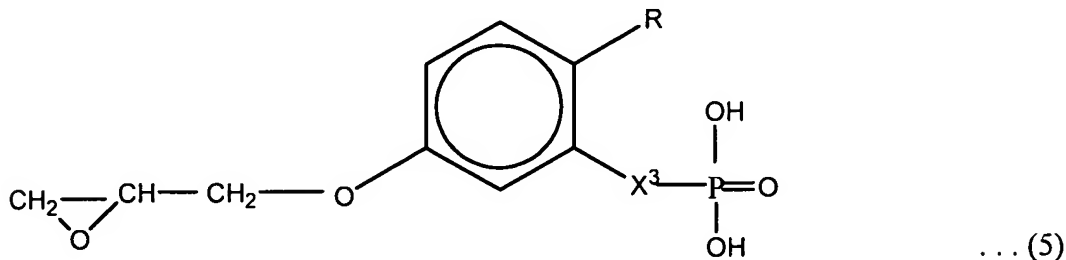


wherein  $\text{X}^1$  and  $\text{X}^2$  respectively represent O or a single bond.

33. (canceled) .

34. (previously presented): A multilayered printed circuit board comprising:  
a conductor circuit and a resin insulating layer serially formed on a substrate in an alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,  
wherein said solder resist layer contains a P atom-containing epoxy resin,  
said P atom-containing epoxy resin is an epoxy resin having a monovalent phosphoric acid residue in one terminal of the P atom-containing epoxy resin and an epoxy group in the other terminal of the P atom-containing epoxy resin, and

said epoxy resin has the following general formula (5):



wherein  $X^3$  represents O or a single bond; and R represents an alkyl of 2 to 8 carbons.

35. (canceled).

36. (previously presented): A multilayered printed circuit board comprising:  
a conductor circuit and a resin insulating layer serially formed on a substrate in an  
alternate fashion and in repetition; and a solder resist layer formed as an outermost layer,  
wherein said solder resist layer contains an elastomer component in a composition  
comprising a resin for said solder resist layer,  
said elastomer component is at least one member selected from the group consisting of  
natural rubber, synthetic rubber, a thermoplastic resin and a thermosetting resin, and  
said elastomer component is separated in micro-phase as to form an island-in-sea  
structure after curing in said solder resist layer.

37-38. (canceled).

39. (previously presented): The multilayered printed circuit board according to claim  
32,  
wherein said solder resist layer contains at least one member selected from the group  
consisting of a silicon compound, an aluminum compound and a magnesium compound.

40. (previously presented): The multilayered printed circuit board according to claim 34,  
wherein said solder resist layer contains at least one member selected from the group consisting of a silicon compound, an aluminum compound and a magnesium compound.